

## AMENDMENTS TO THE CLAIMS

### Claims 1-5 (Cancelled)

6. (Currently Amended) An ~~Integrated Circuit~~ integrated circuit (IC) ~~socket~~ apparatus, comprising:  
an IC socket having a power bar carrier and one or more pin receptacles, a power bar carrier, wherein the power bar carrier includes a first conducting panel electrically coupled to a first plurality of conducting pads[.];  
a first activation mechanism to cause the power bar carrier to engage a power bar of a corresponding IC package with a first force; and  
a second activation mechanism to cause the one or more pin receptacles to engage one or more pins with a second force, wherein the first force and the second force are substantially equivalent.
7. (Currently Amended) The IC ~~socket~~ apparatus of claim 6, wherein the first conducting panel further includes one or more conducting contacts extending beyond the periphery of the conducting panel and coupled to the first conducting panel.
8. (Currently Amended) The ~~socket~~ IC apparatus of ~~Claim~~ claim 7, wherein the first conducting panel and the one or more conducting contacts are stamped from a single conducting foil.
9. (Currently Amended) The IC ~~socket~~ apparatus of claim 7, wherein the one or more conducting contacts are compressibly and electrically engageable.

10. (Currently Amended) The IC ~~socket~~ apparatus of claim 7, wherein the one or more conducting contacts are comprised of a bent conducting material.
11. (Currently Amended) The IC ~~socket~~ apparatus of claim 7, wherein the one or more conducting contacts further comprise a spring constant.
12. (Currently Amended) The IC ~~socket~~ apparatus of claim 6, wherein the power bar carrier further includes a second conducting panel electrically coupled to a second plurality of conducting pads.
13. (Currently Amended) The IC ~~socket~~ apparatus of claim 12, wherein the second conducting panel is insulated from the first conducting panel.
14. (Currently Amended) The IC ~~socket~~ apparatus of claim 6, further comprising an activation mechanism that causes the power bar carrier to engage a power bar of a corresponding IC package.

Claims 15-17 (Cancelled)

18. (Currently Amended) The IC ~~socket of Claim~~ apparatus of claim 15 1, further comprising an activation mechanism that simultaneously causes the power bar carrier to engage a power bar with a first force and causes the one or more pin receptacles to engage one or more pins with a second force.
19. (Currently Amended) The IC ~~socket of Claim~~ apparatus of claim 18, wherein the first force and the second force are substantially equivalent.
20. (Currently Amended) An integrated circuit (IC) power delivery system, comprising:

an IC socket including a power bar carrier and one or more pin receptacles,  
wherein the power bar carrier comprising includes a first conducting panel  
electrically coupled to a first plurality of conducting pads; ~~and~~  
an IC package including a first power plane and a power bar comprising a first  
conducting panel electrically connected to the first power plane along a  
first adjacent edge[.];  
a first activation mechanism to cause the power bar carrier to engage a power bar  
or corresponding IC package with a first force; and  
a second activation mechanism to cause the one or more pin receptacles to engage  
one or more pins with a second force, wherein the first force and the  
second force are substantially equivalent.

21. (Currently Amended) The IC power delivery system of claim 20, wherein the IC package further includes:  
a second power plane electrically isolated from the first power plane; and  
a second conducting panel electrically connected to the second power plane of the IC package along a second adjacent edge.
22. (Currently Amended) The IC power delivery system of ~~Claim~~-claim 21, wherein the power bar further includes a non-conducting insulation panel separating the first conducting panel from the second conducting panel.
23. (Currently Amended) The IC power delivery system of ~~Claim~~-claim 20, wherein the power bar further includes one or more conducting bumps electrically connected to the first conducting panel.

24. (Currently Amended) The IC power delivery system of ~~Claim~~claim 22, wherein the power bar further includes one or more conducting bumps electrically connected to one or more of the first conducting panel and the second conducting panel.
25. (Original) The IC power delivery system of claim 20, wherein the first conducting panel further includes one or more conducting contacts extending beyond the periphery of the conducting panel and coupled to the first conducting panel.
26. (Currently Amended) The IC power delivery system of ~~Claim~~claim 25, wherein the first conducting panel and the one or more conducting contacts are stamped from a single conducting foil.
27. (Original) The IC power delivery system of claim 25, wherein the one or more conducting contacts are compressibly and electrically engageable.
28. (Original) The IC power delivery system of claim 25, wherein the one or more conducting contacts are comprised of a bent conducting material.
29. (Original) The IC power delivery system of claim 25, wherein the one or more conducting contacts further comprise a spring constant.
30. (Currently Amended) The IC power delivery system of claim 20, wherein the power bar carrier further includes a second conducting panel electrically coupled to a second plurality of conducting pads.
31. (Currently Amended) The IC power delivery system of claim 30, wherein the second conducting panel is insulated from the first conducting panel.

32. (Currently Amended) The IC power delivery system of claim 20, further comprising an activation mechanism that causes the power bar carrier to engage a power bar of a corresponding IC package.

Claims 33-35 (Cancelled)

36. (Currently Amended) The IC power delivery system of ~~Claim 33~~ claim 20, further comprising an activation mechanism that simultaneously causes the power bar carrier to engage a power bar with a first force and causes the one or more pin receptacles to engage one or more pins with a second force.
37. (Currently Amended) The IC power delivery system of ~~Claim 36~~ claim 36, wherein the first force and the second force are substantially equivalent.
38. (New) A method, comprising:  
electrically coupling a first conducting panel of a power bar carrier of an  
integrated circuit (IC) socket with a first plurality of conducting pads of  
the power bar carrier, wherein the IC socket further includes one or more  
receptacle pins;  
causing the power bar carrier to engage a power bar of a corresponding IC  
package with a first force using a first activation mechanism; and  
causing the one or more pin receptacles to engage one or more pins with a second  
force, wherein the first force and the second force are substantially  
equivalent.
39. (New) The method of claim 38, wherein the first conducting panel further  
includes one or more conducting contacts extending beyond the periphery of the  
conducting panel and coupled to the first conducting panel.
40. (New) The method of claim 39, wherein the first conducting panel and the one or  
more conducting contacts are stamped from a single conducting foil.

41. (New) The method of claim 39, wherein the one or more conducting contacts are compressibly and electrically engageable.
42. (New) The method of claim 39, wherein the one or more conducting contacts are comprised of a bent conducting material.
43. (New) The IC method of claim 39, wherein the one or more conducting contacts further comprise a spring constant.
44. (New) The method of claim 38, wherein the power bar carrier further includes a second conducting panel electrically coupled to a second plurality of conducting pads.
45. (New) The method of claim 44, wherein the second conducting panel is insulated from the first conducting panel.
46. (New) The method of claim 38, further comprising an activation mechanism that causes the power bar carrier to engage a power bar of a corresponding IC package.